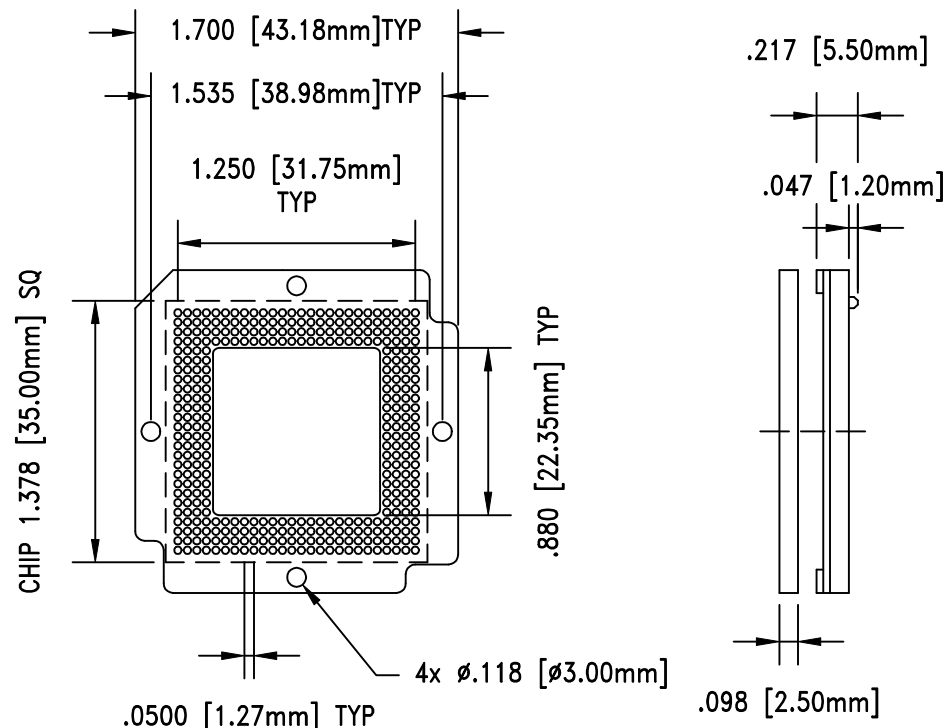
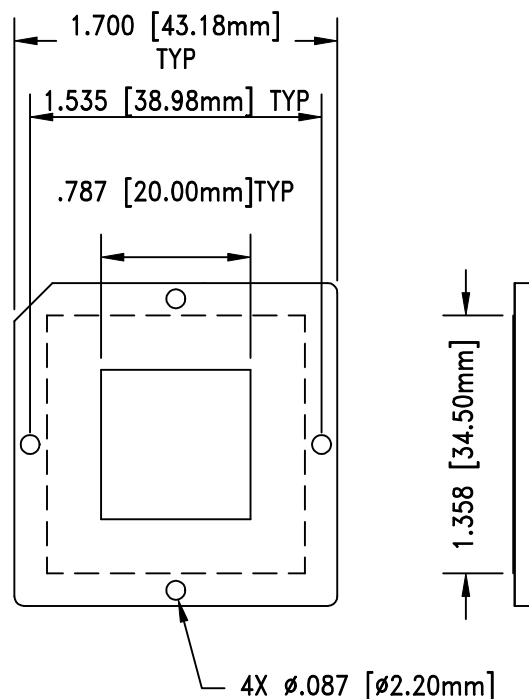


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	4/27/00	M.D.
B	UPDATED PAD LAYOUT AND DIMS	03/30/01	H.N.
C	UPDATED DRAWING	10/10/01	H.N.

SOCKET

SKT772

DOD 4772



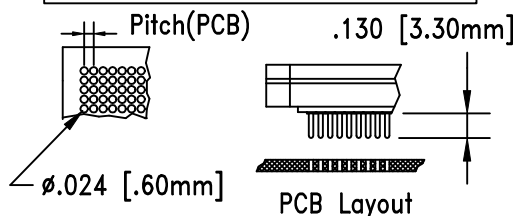
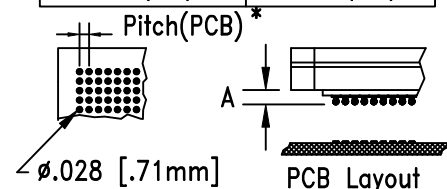
RETENTION FRAME

FOR LOW PROFILE CHIP = <1.00mm THICKNESS W/O SOLDERBALL

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = (-SM)	XX = (-RC)
YY = (-30)	YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])
29= raised SMD ("A" = .197 [5.00mm])

BALL DIAMETER FOR:
-29(RC) = .026 [0.66mm]
-30(SM) = .026 [0.66mm]

PIN DIAMETER FOR:
-70(ET) = .018 [0.45mm]

* The pitch dimension depends on your Ball Grid Array Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 352
LEAD PITCH	= 1.27mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 35.00mm

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.

— VLSI and SMT ADAPTERS and ACCESSORIES —

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TEL:(408)982-0660
FAX:(408)982-0664

SHEET:
1 OF 1

DATE:
10/10/01

REVISION:
C

ASSEMBLY DRAWING

CHECKED:
Perry Munroe

DRAWN:
MIGUEL DELGADILLO

ITEM:
S-BGA-26-352-XX

DESCRIPTION:
BPW-352-2BG026-YY

DO NOT SCALE DRAWING